

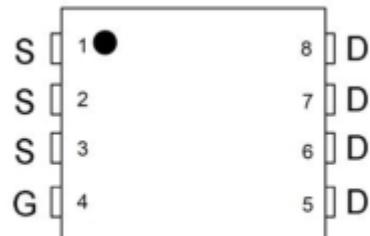
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-20V	6.6mΩ@-4.5V	-45A
	8mΩ@-2.5V	

Feature

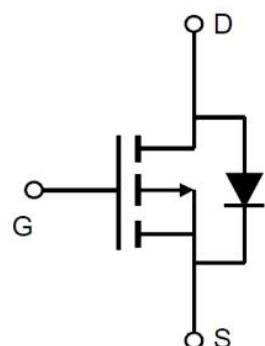
- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Package



PDFNWB3.3×3.3-8L

Circuit diagram





ZL MOSFET

ZL20P07D

Marking



20P07 =Device Code
* =Month Code

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	-45	A
Pulsed Drain Current ¹⁾	I_{DM}	-180	A
Power Dissipation	P_D	38	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3.2	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

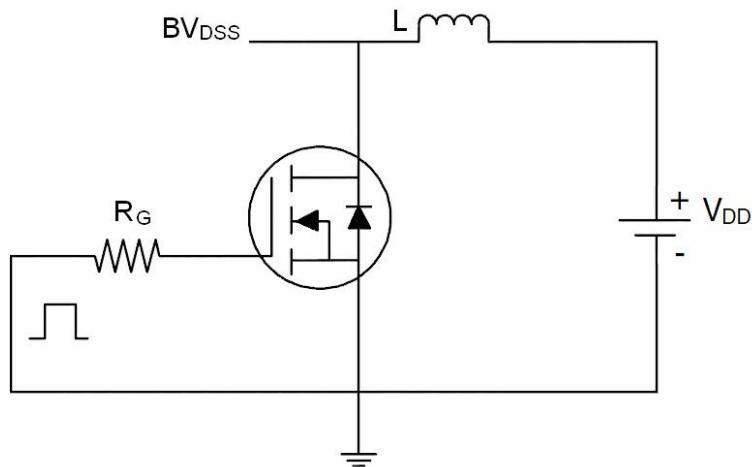
Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

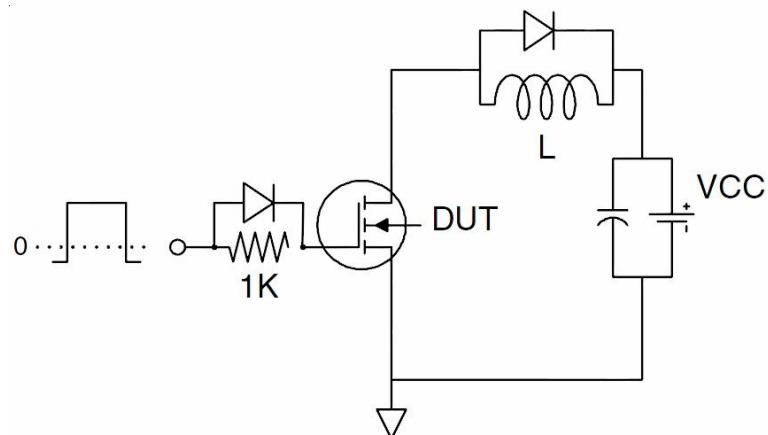
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-20			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 100	μA
On Characteristics						
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.35	-0.65	-1	V
Static Drain-Source On-Resistance ¹	$R_{DS(\text{on})}$	$V_{GS} = -4.5V, I_D = -15A$		6.6	9	$\text{m}\Omega$
		$V_{GS} = -2.5V, I_D = -12A$		8	12	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -10V, V_{GS} = 0V, f = 1\text{MHz}$		4600		pF
Output Capacitance	C_{oss}			460		
Reverse Transfer Capacitance	C_{rss}			459		
Total Gate Charge	Q_g	$V_{DS} = -10V, V_{GS} = -4.5V, I_D = -15A$		46		pF
Gate Source Charge	Q_{gs}			7.3		
Gate Drain Charge	Q_{gd}			10		
Switching Characteristics						
Turn-On Delay Time	$T_{d(on)}$	$V_{DD} = -10V, I_D = -14A, R_{GEN} = 2.7\Omega, V_{GS} = -10V$		8		nS
Rise Time	T_r			59		
Turn-Off Delay Time	$T_{d(off)}$			111		
Fall Time	T_f			43		
Drain-Source Diode Characteristics and Maximum Ratings						
Maximum Continuous Drain to Source Diode Forward Current	I_s				-55	A
Drain to Source Diode Forward Voltage	V_{SD}	$V_{GS} = 0V, I_s = -1A$			-1.2	V
Reverse Recovery Time	t_{rr}	$T_j = 25^\circ\text{C}, I_{SD} = -15A, V_{GS} = 0V, dI/dt = 100A/\mu\text{s}$		18		nS
Reverse Recovery Charge	Q_{rr}			7.7		nC

Test Circuit

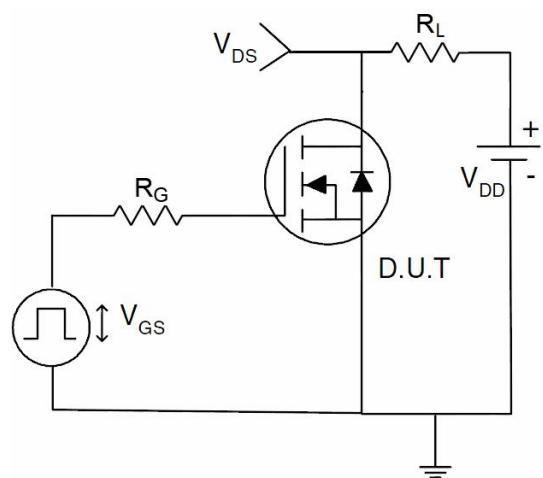
- EAS Test Circuits



- Gate Charge Test Circuit



- Switch Time Test Circuit



Typical Characteristics

Figure 1: Output Characteristics

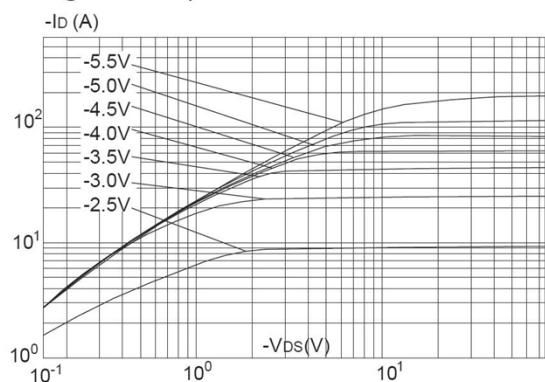


Figure 3: On-resistance vs. Drain Current

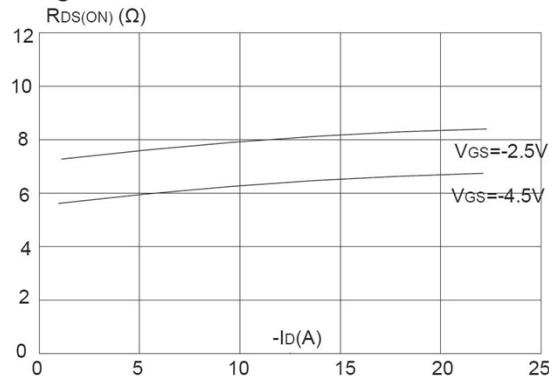


Figure 5: Gate Charge Characteristics

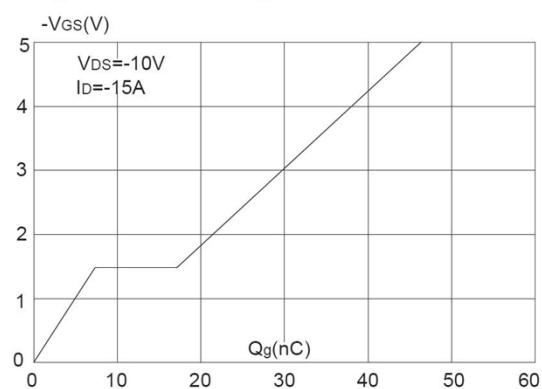


Figure 2: Typical Transfer Characteristics

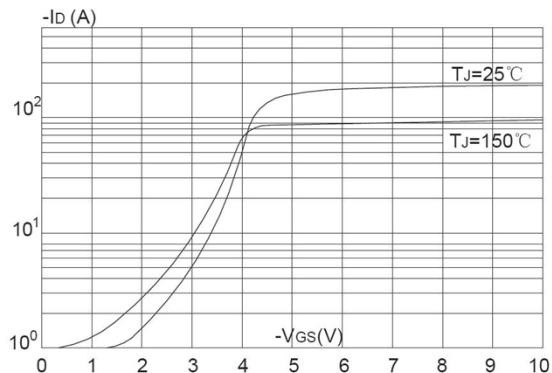


Figure 4: Body Diode Characteristics

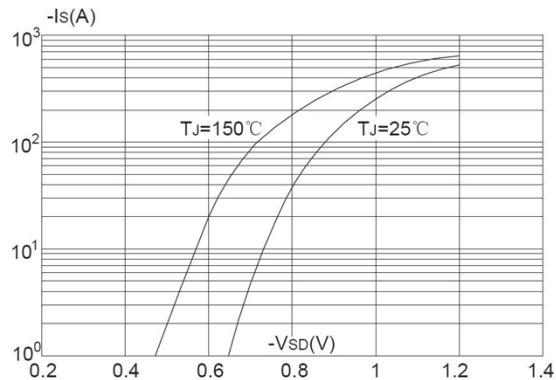


Figure 6: Capacitance Characteristics

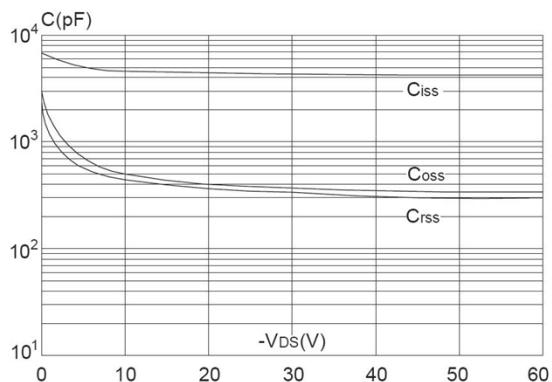


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

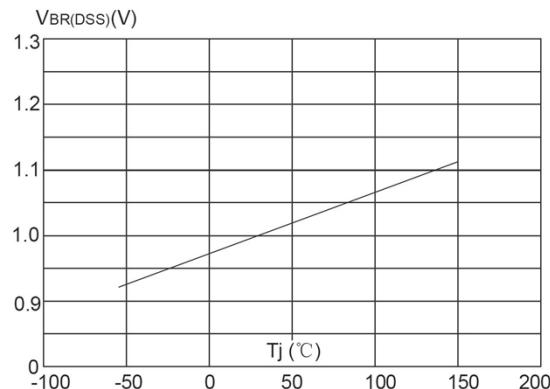


Figure 9: Maximum Safe Operating Area

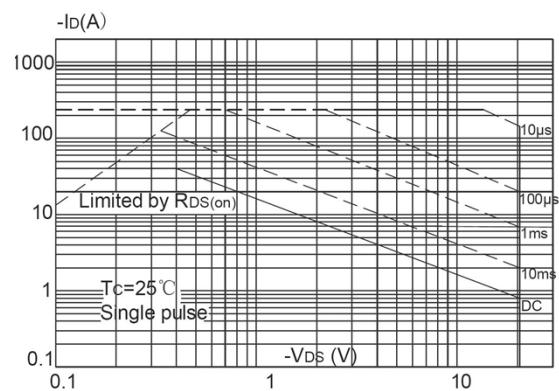


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

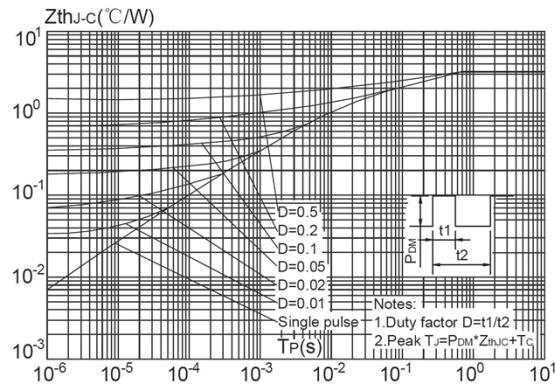


Figure 8: Normalized on Resistance vs. Junction Temperature

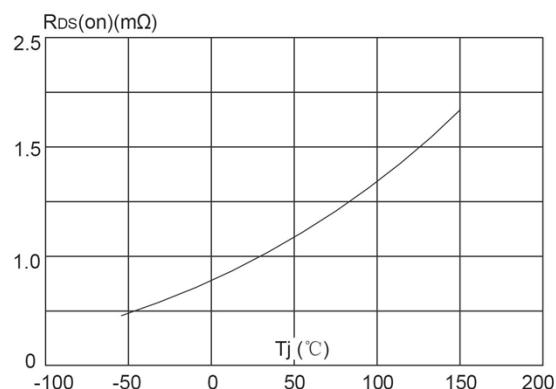
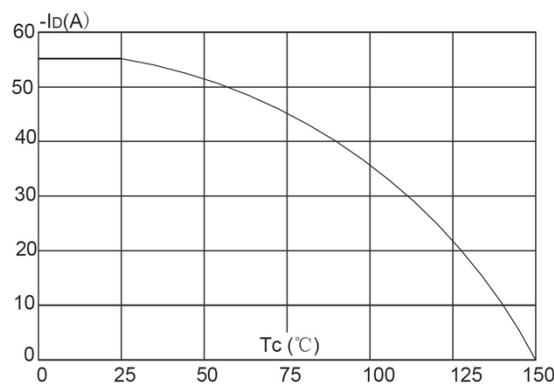
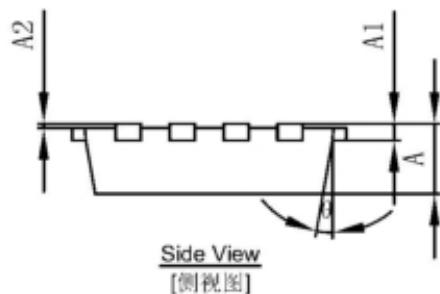
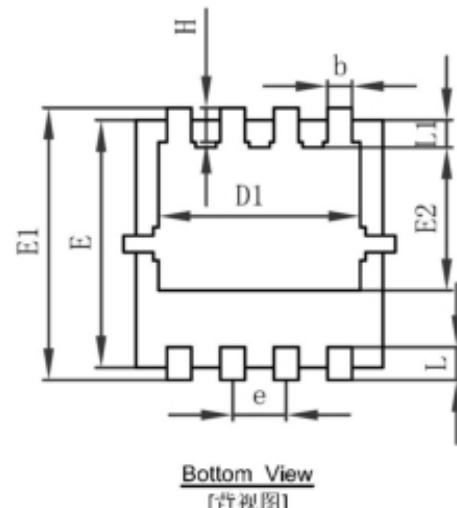
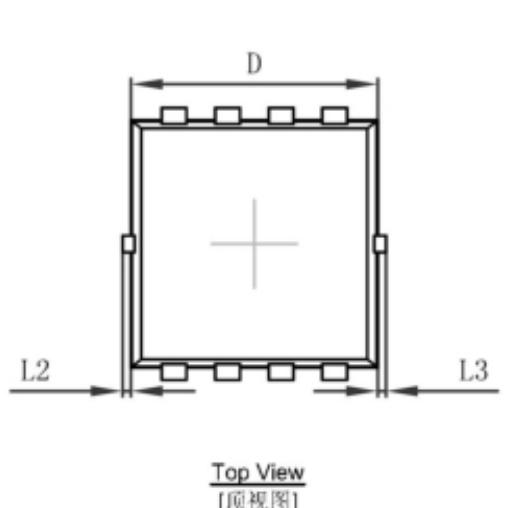


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



PDFNWB3.3×3.3-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.			0.006 REF.
A2	0~0.05			0~0.002
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100			0~0.004
L3	0~0.100			0~0.004
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°